

ABSTRACT OF THE DISCLOSURE

A lead frame comprises a stage for mounting a semiconductor chip thereon, a plurality of leads arranged in the periphery of the stage, and a plurality of lead interconnection members (e.g., dam bars) for interconnecting the leads, wherein a plurality of through holes are formed to penetrate through the lead frame in a thickness direction with respect to the leads or the lead interconnection members so as to allow a plurality of cutting lines to pass therethrough, whereby the leads are subjected to cutting and are made electrically independent of each other. A semiconductor package of a QFN type is produced by enclosing the lead frame within a molded resin, from which the leads are partially exposed to the exterior and are subjected to plating and are then subjected to cutting at the cutting lines.